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cont

~~-- Claim 17(new) The die attach package of claim 1 wherein the die being at-
tached includes components attached to the die. --~~

REMARKS

The two additional new claims 16 and 17 add some specificity to the original claims that read directly on die varieties that are commonly used in the art – a typical integrated circuit die and a die or substrate that carries discrete components. No new matter is added as such dies have been routinely used for many decades.

Please charge any additional fee occasioned by this paper to our Deposit Account No. 03-1237.

Respectfully submitted,

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